

High Performance FR4 Laminate: **R - 1755V**
Prepreg: **R - 1650V**

Standard size warp weft mm	Copper foil thickness	Laminate thickness	Thickness tolerance
920 x 1220	0,012 mm	Thin laminates from 0,06 mm up to 0,76mm (excluding Copper foil thickness)	according to IPC - 4101 C B - (C)
1110 x 1220	0,018 mm		
1280 x 1070	0,035 mm	_____	
1240 x 1230*	0,070 mm	Rigid laminates from 0,8 mm up to 1,6 mm (including Copper foil thickness)	according to IPC - 4101 C L - (M)
	0,105 mm		



* Only cut panels Other thicknesses on request

[**Features**]

- ▶ High performance FR4 material for PCB production
- ▶ Tg 170° C by DSC method
- ▶ Phenolic cured, excellent through-hole reliability, low CTE-Z
- ▶ Excellent heat resistance, low water absorption
- ▶ Excellent CAF resistance
- ▶ For lead free assembly
- ▶ Conform to the most important international Standards
IPC-4101B/126, UL 94, IPC-4562, UL 746
- ▶ Clear prepreg available
- ▶ UV-blocking
- ▶ Workability: with standard FR4 process

[**Applications**]

Automotive, Network equipment (server, routers), Measuring instruments, etc